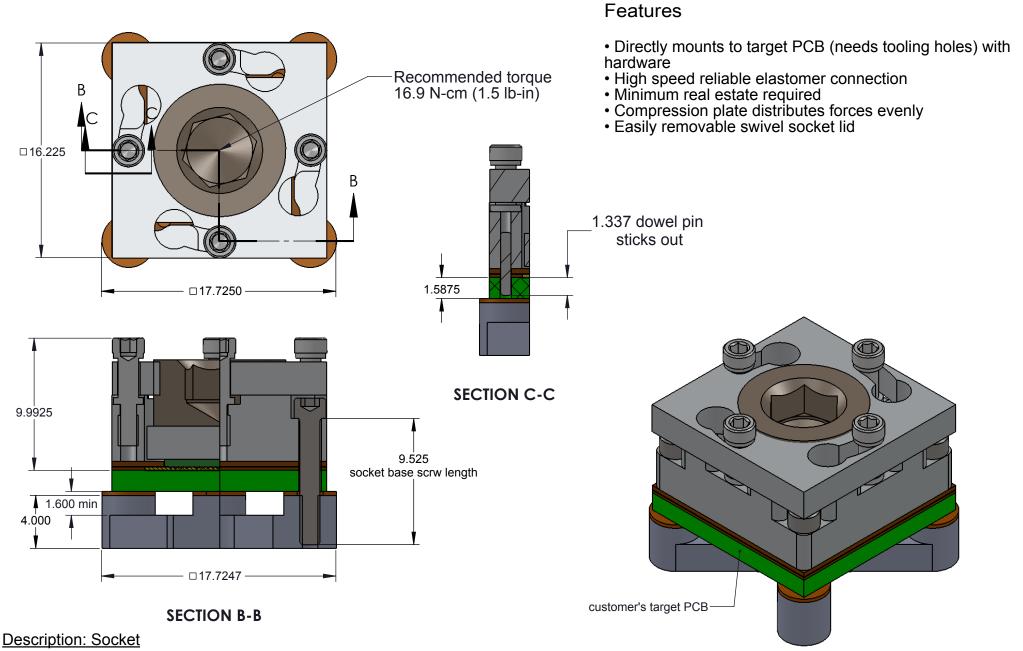
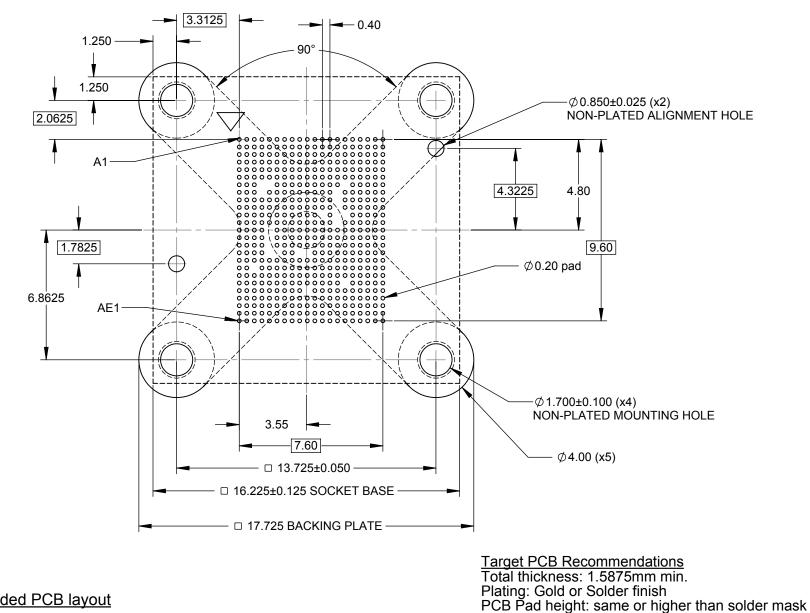
## **GHz BGA SOCKET - direct mount, solderless**



Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams. <u>Tolerances:</u> Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SG25-BGA-2003 Drawing	Finish: N/A Weight: 7.74	STATUS: Released	SHEET: 1 OF 4	REV. A
Ironwood Electronics, Inc. Tele: (800) 404-0204		ENG: E. Smolentseva	DRAWN BY: M. Raske	SCALE: 3.5:1
www.ironwoodelectronics.com		FILE: SG25-BGA-2003 Dwg	DATE: 4/16/2015	

## <u>\*Note: BGA pattern is shifted by 0.25 to</u> <u>right with respect to the mounting holes.</u>

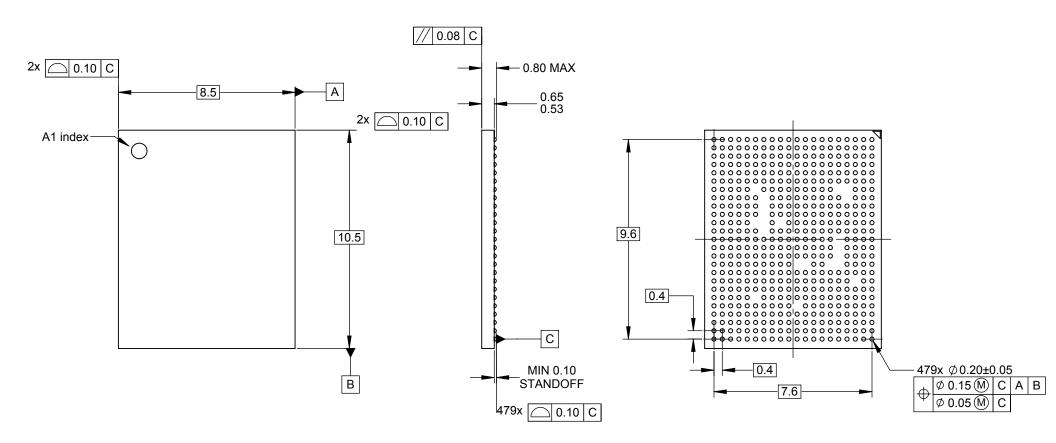


**Description: Recommended PCB layout** 

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams. <u>Tolerances:</u> Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all

<u>Tolerances</u>: Hole diameters ±0.03mm ±0.001 j, Pitches (from true position) ±0.025mm ±0.001 j, substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SG	5-BGA-2003 Drawing Material: N/A		STATUS: Released	SHEET: 2 OF 4	REV. A
Tele	Ironwood Electronics, Inc. Tele: (800) 404-0204	Weight: 7.74	ENG: E. Smolentseva	DRAWN BY: M. Raske	SCALE: 5:1
	www.ironwoodelectronics.com		FILE: SG25-BGA-2003 Dwg	DATE: 4/16/2015	

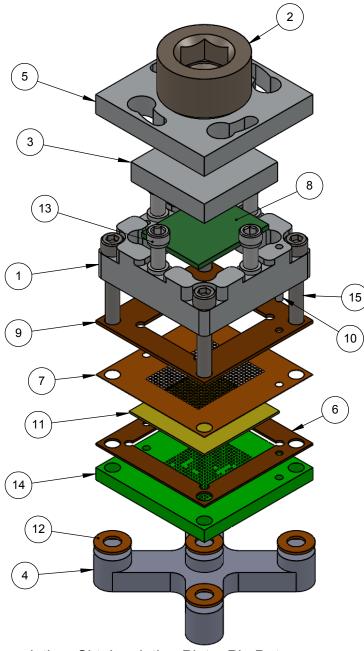


## **Description: BGA**

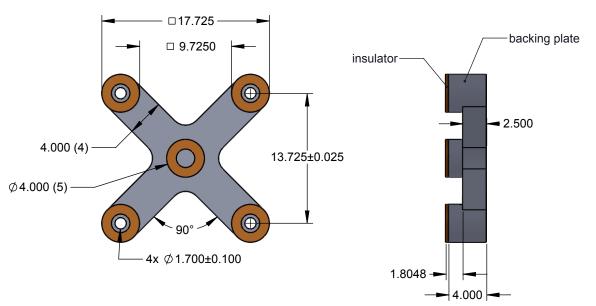
Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

<u>Tolerances:</u> Hole diameters  $\pm 0.03$ mm [ $\pm 0.001^{"}$ ], Pitches (from true position)  $\pm 0.025$ mm [ $\pm 0.001^{"}$ ], substrate thickness tolerance  $\pm 10\%$ , all other tolerances  $\pm 0.13$ mm [ $\pm 0.005^{"}$ ] unless stated otherwise. Materials and specifications are subject to change without notice.

SG	G25-BGA-2003 Drawing Material: N/A		STATUS: Released	SHEET: 3 OF 4	REV. A
Tele: (800) 404	Ironwood Electronics, Inc.	Finish: N/A Weight: 7.74	ENG: E. Smolentseva	DRAWN BY: M. Raske	SCALE: 5.5:1
	www.ironwoodelectronics.com		FILE: SG25-BGA-2003 Dwg	DATE: 4/16/2015	



ITEM NO.	DESCRIPTION	Material
1	Socket Base	7075-T6 Aluminum Alloy
2	Compression Screw M10	7075-T6 Alumium Alloy
3	Compression Plate 11x11mm IC 2.5mm thick	7075-T6 Aluminum Alloy
4	"X" shaped Backing Plate for 11mm chip	7075-T6 (SN)
5	Socket Lid Swivel 11mm IC	7075-T6 Aluminum Alloy
6	Elastomer Guide	Kapton Polyimide/Cirlex
7	Ball Guide for 20x25 0.4mm pitch array	Kapton Polyimide
8	Customer's device	FR4 Standard
9	IC Guide	Kapton Polyimide/Cirlex
10	Dowel Pin, 1/32" x 3/16", SS	Chrome Stainless Steel
11	0.25mm thick, 0.05x 0.05mm pitch elastomer	20 Micron dia gold plated brass filaments arranged symettrically in a silicon rubber (63.5 degree angle), Thickness: 0.25mm
12	Insulating washer, 4mm OD.	Kapton Polyimide/Cirlex
13	#0-80 Shoulder Screw, 0.090" thread length	Stainless Steel (303)
14	Customer's target PCB	FR4 High temp
15	#0-80 X .375 LG, SOC HD CAP SCREW, ALLOY STL, BLK OXIDE	Alloy Steel



## Description: Skt, Insulation Plate, Pin Det

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams. <u>Tolerances</u>: Hole diameters  $\pm 0.03$ mm [ $\pm 0.001^{\circ}$ ], Pitches (from true position)  $\pm 0.025$ mm [ $\pm 0.001^{\circ}$ ], substrate thickness tolerance  $\pm 10\%$ , all other tolerances  $\pm 0.13$ mm [ $\pm 0.005^{\circ}$ ] unless stated otherwise. Materials and specifications are subject to change without notice.

SG25-BGA-2003 Drawing	Material: N/A	STATUS: Released	SHEET: 4 OF 4	REV. A
Ironwood Electronics, Inc. Tele: (800) 404-0204	Weight: 7.74	ENG: E. Smolentseva	DRAWN BY: M. Raske	SCALE: 2.5:1
www.ironwoodelectronics.com		FILE: SG25-BGA-2003 Dwg	DATE: 4/16/2015	